

## 54F/74F403A First-In First-Out (FIFO) Buffer Memory

## **General Description**

The 'F403A is an expandable fall-through type high-speed First-In First-Out (FIFO) Buffer Memory optimized for high-speed disk or tape controllers and communication buffer applications. It is organized as 16-words by 4-bits and may be expanded to any number of words or any number of bits in multiples of four. Data may be entered or extracted asynchronously in serial or parallel, allowing economical implementation of buffer memories.

The 'F403A has TRI-STATE® outputs which provide added versatility and is fully compatible with all TTL families.

#### **Features**

- Serial or parallel input
- Serial or parallel output
- Expandable without external logic
- **TRI-STATE outputs**
- Fully compatible with all TTL families
- Slim 24-pin package
- 9403A replacement
- Guaranteed 4000V minimum ESD protection

Ordering Code: See Section 5
Connection Diagrams

¥R - 11

GND

12

#### Pin Assignment for DIP and SOIC 24 ORE 23 22 D3 · $D_{S}$ 18 Qz CPSI-17 ŌĒ - CPSO ĪĒS -16 πs-- ŌES 10 15

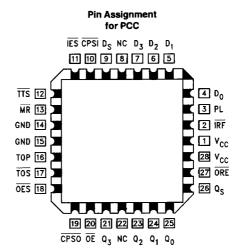
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TOS

TOP

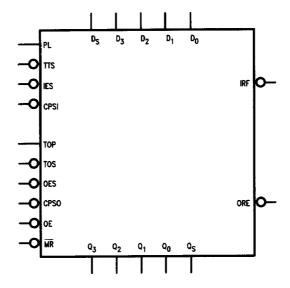
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## **Logic Symbol**

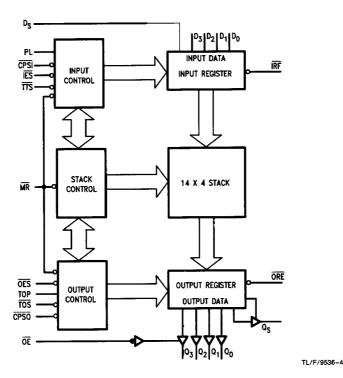


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## Unit Loading/Fan Out: See Section 2 for U.L. definitions

		54F/74F				
Pin Names	Description	U.L. HIGH/LOW	input I <sub>IH</sub> /I <sub>IL</sub> Output I <sub>OH</sub> /I <sub>OL</sub>			
D <sub>0</sub> -D <sub>3</sub>	Parallel Data Inputs	1.0/0.667	20 μΑ/400 μΑ			
Ds	Serial Data Input	1.0/0.667	20 μΑ/400 μΑ			
PĽ	Parallel Load Input	1.0/0.667	20 μΑ/400 μΑ			
CPSI	Serial Input Clock	1.0/0.667	20 μΑ/400 μΑ			
ĪĒS	Serial Input Enable	1.0/0.667	20 μΑ/400 μΑ			
TTS	Transfer to Stack Input	1.0/0.667	20 μΑ/400 μΑ			
OES	Serial Output Enable	1.0/0.667	20 μΑ/400 μΑ			
TOS	Transfer Out Serial	1.0/0.667	20 μΑ/400 μΑ			
TOP	Transfer Out Parallel	1.0/0.667	20 μΑ/400 μΑ			
MR	Master Reset	1.0/0.667	20 μΑ/400 μΑ			
ŌĒ	Output Enable	1.0/0.667	20 μΑ/400 μΑ			
CPSO	Serial Output Clock	1.0/0.667	20 μΑ/400 μΑ			
Q <sub>0</sub> -Q <sub>3</sub>	Parallel Data Outputs	285/26.7	5.7 mA/16 mA			
Qs	Serial Data Output	285/26.7	5.7 mA/16 mA			
IRF	Input Register Full	20/13.3	−400 μA/8 mA			
ORE	Output Register Empty	20/13.3	-400 μA/8 mA			

#### **Block Diagram**



### **Functional Description**

As shown in the block diagram the 'F403A consists of three sections:

- An Input Register with parallel and serial data inputs as well as control inputs and outputs for input handshaking and expansion.
- A 4-bit wide, 14-word deep fall-through stack with selfcontained control logic.
- An Output Register with parallel and serial data outputs as well as control inputs and outputs for output handshaking and expansion.

Since these three sections operate asynchronously and almost independently, they will be described separately below.

#### INPUT REGISTER (DATA ENTRY)

The Input Register can receive data in either bit-serial or in 4-bit parallel form. It stores this data until it is sent to the fall-through stack and generates the necessary status and control signals.

Figure 1 is a conceptual logic diagram of the input section. As described later, this 5-bit register is initialized by setting

the  $F_3$  flip-flop and resetting the other flip-flops. The  $\overline{Q}$  output of the last flip-flop (FC) is brought out as the 'Input Register Full' output ( $\overline{||}\overline{R}\overline{P}|$ ). After initialization this output is HIGH.

**Parallel Entry**—A HIGH on the PL input loads the  $D_0-D_3$  inputs into the  $F_0-F_3$  flip-flops and sets the FC flip-flop. This forces the  $\overline{\mbox{IRF}}$  output LOW indicating that the input register is full. During parallel entry, the  $\overline{\mbox{CPSI}}$  input must be LOW. If parallel expansion is not being implemented,  $\overline{\mbox{IES}}$  must be LOW to establish row mastership (see Expansion section).

Serial Entry—Data on the D<sub>S</sub> input is serially entered into the F<sub>3</sub>, F<sub>2</sub>, F<sub>1</sub>, F<sub>0</sub>, FC shift register on each HIGH-to-LOW transition of the CPSI clock input, provided IES and PL are LOW.

After the fourth clock transition, the four data bits are located in the four flip-flops,  $F_0-F_3$ . The FC flip-flop is set, forcing the IRF output LOW and internally inhibiting CPSI clock pulses from affecting the register, Figure 2 illustrates the final positions in a 'F403A resulting from a 64-bit serial bit train.  $B_0$  is the first bit,  $B_6$ 3 the last bit.

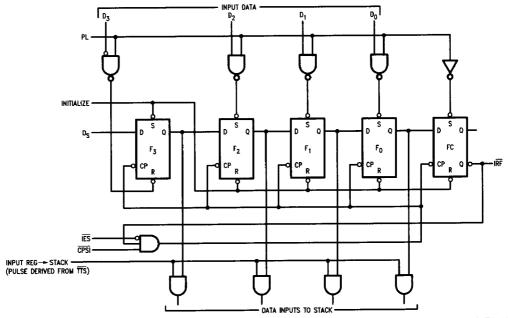


FIGURE 1. Conceptual Input Section

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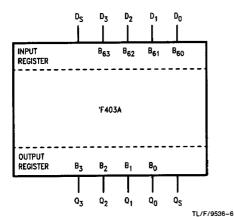


FIGURE 2. Final Positions in a 'F403A Resulting from a 64-Bit Serial Train

**Transfer to the Stack**—The outputs of Flip-Flops  $F_0$ – $F_3$  feed the stack. A LOW level on the  $\overline{TTS}$  input initiates a 'fall-

through' action. If the top location of the stack is empty, data is loaded into the stack and the input register is re-initialized. Note that this initialization is postponed until PL is LOW again. Thus, automatic FIFO action is achieved by connecting the IRF output to the TTS input.

An RS Flip-Flop (the Request Initialization Flip-Flop shown in Figure 10) in the control section records the fact that data has been transferred to the stack. This prevents multiple entry of the same word into the stack despite the fact the IRF and  $\overline{\text{TTS}}$  may still be LOW. The Request Initialization Flip-Flop is not cleared until PL goes LOW. Once in the stack, data falls through the stack automatically, pausing only when it is necessary to wait for an empty next location. In the 'F403A as in most modern FIFO designs, the  $\overline{\text{MR}}$  input only initializes the stack control section and does not clear the data.

#### **OUTPUT REGISTER (DATA EXTRACTION)**

The Output Register receives 4-bit data words from the bottom stack location, stores it and outputs data on a TRI-STATE 4-bit parallel data bus or on a TRI-STATE serial data bus. The output section generates and receives the necesary status and control signals. *Figure 3* is a conceptual logic diagram of the output section.

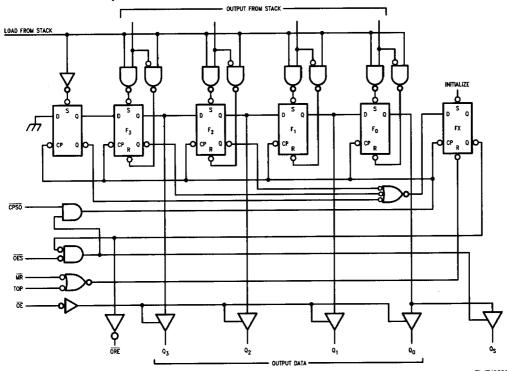


FIGURE 3. Conceptual Output Section

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Parallel Data Extraction-When the FIFO is empty after a LOW pulse is applied to MR, the Output Register Empty (ORE) output is LOW. After data has been entered into the FIFO and has fallen through to the bottom stack location, it is transferred into the Output Register provided the 'Transfer Out Parallel' (TOP) input is HIGH. As a result of the data transfer ORE goes HIGH, indicating valid data on the data outputs (provided the TRI-STATE buffer is enabled). TOP can now be used to clock out the next word. When TOP goes LOW, ORE will go LOW indicating that the output data has been extracted, but the data itself remains on the output bus until the next HIGH level at TOP permits the transfer of the next word (if available) into the Output Register. During parallel data extraction CPSO should be LOW. TOS should be grounded for single slice operation or connected to the appropriate ORE for expanded operation (see Expansion

TOP is not edge triggered. Therefore, if TOP goes HIGH before data is available from the stack, but data does become available before TOP goes LOW again, that data will be transferred into the Output Register. However, internal

control circuitry prevents the same data from being transferred twice. If TOP goes HIGH and returns to LOW before data is available from the stack, ORE remains LOW indicating that there is no valid data at the outputs.

Serial Data Extraction-When the FIFO is empty after a LOW pulse is applied to MR, the Output Register Empty (ORE) output is LOW. After data has been entered into the FIFO and has fallen through to the bottom stack location, it is transferred into the Output Register provided TOS is LOW and TOP is HIGH. As a result of the data transfer ORE goes HIGH indicating valid data in the register. The TRI-STATE Serial Data Output, QS, is automatically enabled and puts the first data bit on the output bus. Data is serially shifted out on the HIGH-to-LOW transition of CPSO. To prevent false shifting, CPSO should be LOW when the new word is being loaded into the Output Register. The fourth transition empties the shift register, forces ORE output LOW and disables the serial output, QS (refer to Figure 3). For serial operation the ORE output may be tied to the TOS input, requesting a new word from the stack as soon as the previous one has been shifted out.

#### **EXPANSION**

**Vertical Expansion**—The 'F403A may be vertically expanded to store more words without external parts. The interconnection is necessary to form a 46-word by 4-bit FIFO are shown in *Figure 4*. Using the same technique, and FIFO

of (15n+1)-words by 4-bits can be constructed, where n is the number of devices. Note that expansion does not sacrifice any of the 'F403A's flexibility for serial/parallel input and output.

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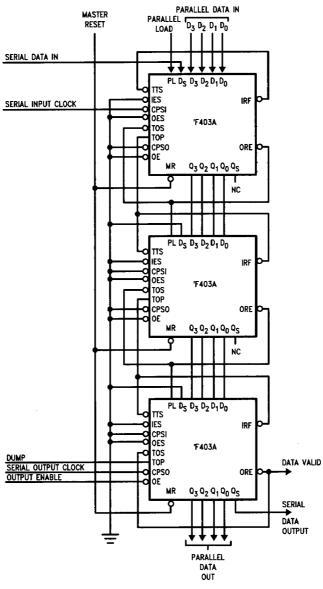


FIGURE 4. A Vertical Expansion Scheme

Horizontal and Vertical Expansion—The 'F403A can be expanded in both the horizontal and vertical directions without any external parts and without sacrificing any of its FIFO's flexibility for serial/parallel input and output. The interconnections necessary to form a 31-word by 16-bit FIFO are shown in Figure 6. Using the same technique, any FIFO of (15m+1)-words by (4n)-bits can be constructed, where m is the number of devices in a column and n is the number of devices in a row. Figures 7 and 8 show the timing diagrams for serial data entry and extraction for the 31-word by 16-bit FIFO shown in Figure 6. The final position of data after serial insertion of 496 bits into the FIFO array of Figure 6 is shown in Figure 9.

Interlocking Circuitry—Most conventional FIFO designs provide status signals analogous to IRF and ORE. However, when these devices are operated in arrays, variations in unit to unit operating speed require external gating to assure all devices have completed an operation. The 'F403A incorporates simple but effective 'master/slave' interlocking circuitry to eliminate the need for external gating.

In the 'F403A array of Figure 6 devices 1 and 5 are defined as 'row masters' and the other devices are slaves to the master in their row. No slave in a given row will initialize its Input Register until it has received LOW on its IES input from a row master or a slave of higher priority.

In a similar fashion, the  $\overline{\text{ORE}}$  outputs of slaves will not go HIGH until their  $\overline{\text{OES}}$  inputs have gone HIGH. This interlock-

ing scheme ensures that new input data may be accepted by the array when the IRF output of the final slave in that row goes HIGH and that output data for the array may be extracted when the ORE of the final slave in the output row goes HIGH.

The row master is established by connecting its IES input to ground while a slave receives its IES input from the IRF output of the next higher priority device. When an array of 'F403A FIFOs is initialized with a LOW on the MR inputs of all devices, the IRF outputs of all devices will be HIGH. Thus, only the row master receives a LOW on the IES input during initialization. Figure 10 is a conceptual logic diagram of the internal circuitry which determines master/slave operation. Whenever MR and IES are LOW, the Master Latch is set. Whenever TTS goes LOW the Request Initialization Flip-Flop will be set. If the Master Latch is HIGH, the Input Register will be immediately initialized and the Request Initialization Flip-Flop reset, If the Master Latch is reset, the Input Register is not initialized until IES goes LOW. In array operation, activating the TTS initiates a ripple input register initialization from the row master to the last slave.

A similar operation takes place for the output register. Either a  $\overline{TOS}$  or TOP input initiates a load-from-stack operation and sets the  $\overline{ORE}$  Request Flip-Flop. If the Master Latch is set, the last Output Register Flip-Flop is set and  $\overline{ORE}$  goes HIGH. If the Master Latch is reset, the  $\overline{ORE}$  output will be LOW until an  $\overline{OES}$  input is received.

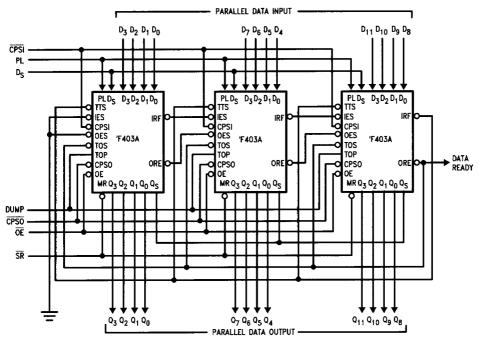


FIGURE 5. A Horizontal Expansion Scheme

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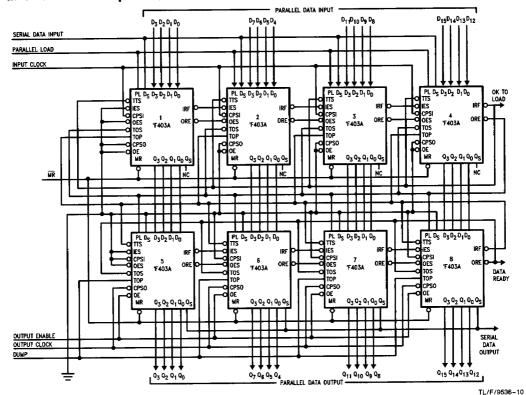
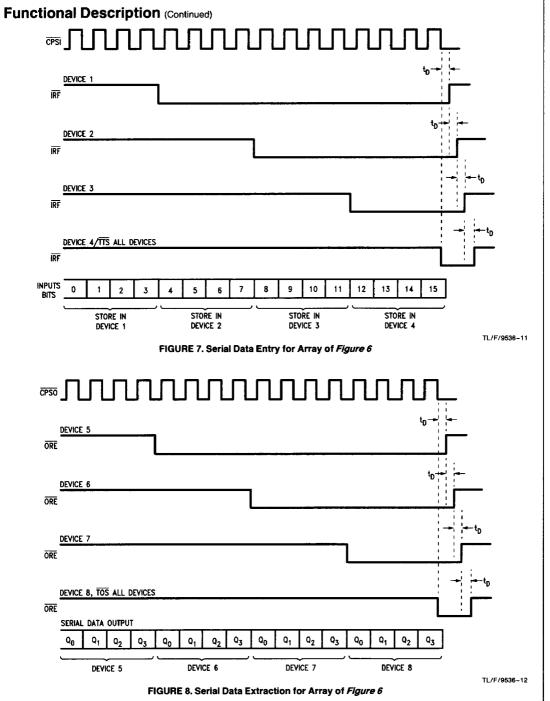


FIGURE 6. A 31 x 16 FIFO Array



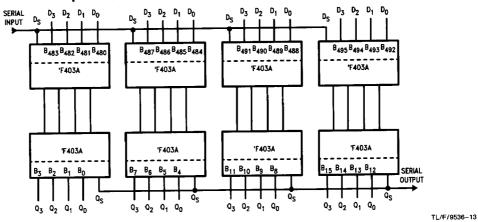


FIGURE 9. Final Position of a 496-Bit Serial Input

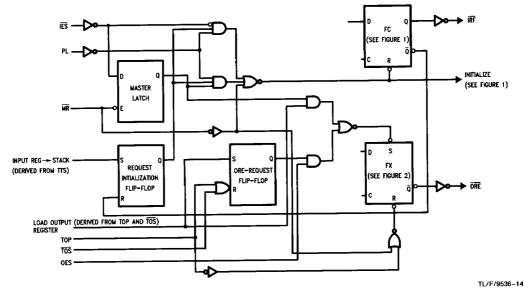


FIGURE 10. Conceptual Diagram, Interlocking Circuitry

#### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature -65°C to +150°C

Ambient Temperature under Bias -55°C to +125°C

Junction Temperature under Bias -55°C to +175°C

V<sub>CC</sub> Pin Potential to

Ground Pin -0.5V to +7.0V

Input Voltage (Note 2) -0.5V to +7.0V

Input Current (Note 2) -30 mA to +5.0 mA

Voltage Applied to Output

in HIGH State (with  $V_{CC} = 0V$ )

Standard Output -0.5V to V<sub>CC</sub>
TRI-STATE Output -0.5V to +5.5V

Current Applied to Output

in LOW State (Max) twice the rated  $I_{OL}$  (mA)

ESD Last Passing Voltage (Min) 4000

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

## Recommended Operating Conditions

Free Air Ambient Temperature

Military -55°C to +125°C Commercial 0°C to +70°C

niv Voltage

Supply Voltage

Military + 4.5V to + 5.5V Commercial + 4.5V to + 5.5V

## **DC Electrical Characteristics**

Combal	Parameter		54F/74F			Units	Vcc	Conditions	
Symbol			Min	Тур	Max	Units	▼CC	Conditions	
V <sub>IH</sub>	Input HIGH Voltage		2.0			٧		Recognized as a HIGH Signa	
V <sub>IL</sub>	Input LOW Volta	ıge			0.8	٧		Recognized as a LOW Signal	
V <sub>CD</sub>	Input Clamp Dio	de Voltage			-1.5	٧	Min	I <sub>IN</sub> = -18 mA	
V <sub>OH</sub>	Output HIGH Voltage	54F 10% V <sub>CC</sub> 54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 5% V <sub>CC</sub> 74F 5% V <sub>CC</sub>	2.4 2.4 2.5 2.5 2.7 2.7			٧	Min	$\begin{split} I_{OH} &= -400~\mu\text{A}~(\text{IRF},\overline{\text{ORE}})\\ I_{OH} &= -2.0~\text{mA}~(Q_{\text{n}},Q_{\text{s}})\\ I_{OH} &= -400~\mu\text{A}~(\text{IRF},\overline{\text{ORE}})\\ I_{OH} &= -5.7~\text{mA}~(Q_{\text{n}},Q_{\text{s}})\\ I_{OH} &= -400~\mu\text{A}~(\text{IRF},\overline{\text{ORE}})\\ I_{OH} &= -5.7~\text{mA}~(Q_{\text{n}},Q_{\text{s}}) \end{split}$	
V <sub>OL</sub>	Output LOW Voltage	54F 10% V <sub>CC</sub> 54F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub> 74F 10% V <sub>CC</sub>			0.4 0.4 0.5 0.5	٧	Min	$\begin{split} I_{OL} &= 4 \text{ mA (IRF, } \overline{ORE}) \\ I_{OL} &= 8 \text{ mA (} Q_n, Q_s) \\ I_{OL} &= 8 \text{ mA (} \overline{IRF, } \overline{ORE}) \\ I_{OL} &= 16 \text{ mA (} Q_n, Q_s) \end{split}$	
Iн	Input HIGH Curr	ent			20	μΑ	Max	$V_{IN} = 2.7V$	
IBVI	Input HIGH Curr Breakdown Test				100	μΑ	Max	V <sub>IN</sub> = 7.0V	
I <sub>IL</sub>	Input LOW Current				-0.4	mA	Max	V <sub>IN</sub> = 0.5V	
lozh	Output Leakage	Current			50	μΑ	Max	V <sub>OUT</sub> = 2.7V	
lozL	Output Leakage	Current			-50	μΑ	Max	$V_{OUT} = 0.5V$	
los	Output Short-Cir	rcuit Current	-20		-130	mA	Max	V <sub>OUT</sub> = 0V	
I <sub>CEX</sub>	Output HIGH Le	akage Current			250	μΑ	Max	V <sub>OUT</sub> = V <sub>CC</sub>	
loc <sub>L</sub>	Power Supply C	urrent			170	mA	Max	V <sub>O</sub> = LOW	

# AC Electrical Characteristics

Symbol	Parameter	74F  T <sub>A</sub> = +25°C  V <sub>CC</sub> = +5.0V  C <sub>L</sub> = 50 pF		5-	4F	74	4F	]	
				T <sub>A</sub> , V <sub>CC</sub> = Mil C <sub>L</sub> = 50 pF		T <sub>A</sub> , V <sub>CC</sub> = Com C <sub>L</sub> = 50 pF		Units	Fig. No.
		Min	Max	Min	Max	Min	Max		
t <sub>PHL</sub>	Propagation Delay, Negative-Going CPSI to IRF Output	7.5	14.0			7.0	15.0	ns	403-a, l
t <sub>PLH</sub>	Propagation Delay, Negative-Going TTS to IRF	11.0	20.5			10.0	22.5		
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay, Negative-Going CPSO to Q <sub>S</sub> Output	8.5 8.0	17.0 14.5			7.5 7.0	18.5 15.5	ns	403-c,
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay, Positive-Going TOP to Outputs Q <sub>0</sub> -Q <sub>3</sub>	10.0 8.5	18.0 15.5			9.0 8.0	20.0 16.5	ns	403-e
<sup>t</sup> PHL	Propagation Delay, Negative-Going CPSO to ORE	9.5	17.5			9.0	19.0	ns	403-с,
<sup>t</sup> PHL	Propagation Delay, Negative-Going TOP to ORE	8.0	15.0			7.5	16.5	ns	403-6
t <sub>PLH</sub>	Propagation Delay, Positive-Going TOP to ORE	12.5	22.0			11.5	25.0		
<sup>†</sup> PLH	Propagation Delay, Negative-Going TOS to Positive Going ORE	12.5	22.0			11.0	25.0	ns	403-c,
t <sub>PHL</sub>	Propagation Delay, Positive-Going PL to Negative-Going IRF	7.0	13.0			6.5	14.0	ns	403-g,
t <sub>PLH</sub>	Propagation Delay, Negative-Going PL to Positive-Going IRF	9.5	17.0			8.5	19.5		

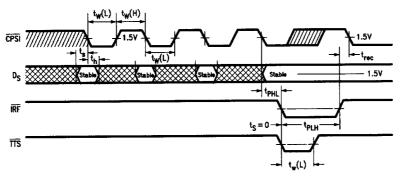
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		74	F	54F		74F			
Symbol	Parameter	T <sub>A</sub> = +25°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50 pF		T <sub>A</sub> , V <sub>CC</sub> = Mil C <sub>L</sub> = 50 pF		T <sub>A</sub> , V <sub>CC</sub> = Com C <sub>L</sub> = 50 pF		Units	Fig. No.
		Min	Max	Min	Max	Min	Max		
t <sub>PLH</sub>	Propagation Delay, Positive-Going OES to ORE	10.0	18.0			9.0	20.5	ns	
t <sub>PLH</sub>	Propagation Delay, Positive-Going IES to Positive-Going IRF	8.5	15.5			7.5	17.5	ns	403-h
t <sub>PLH</sub>	Propagation Delay, MR to IRF	8.0	15.0			7.5	17.0	ns	
t <sub>PHL</sub>	Propagation Delay, MR to ORE	9.0	16.0			8.0	17.5	ns	
t <sub>PZH</sub>	Propagation Delay, <del>OE</del> to Q <sub>0</sub> , Q <sub>1</sub> , Q <sub>2</sub> , Q <sub>3</sub>	2.5 2.5	6.5 7.5			2.0 2.0	8.0 8.5		
t <sub>PHZ</sub>	Propagation Delay,  OE to Q <sub>0</sub> , Q <sub>1</sub> , Q <sub>2</sub> , Q <sub>3</sub>	2.5 2.5	6.5 7.5			2.0 2.0	8.0 8.0	- ns	
t <sub>PZH</sub> t <sub>PZL</sub>	Propagation Delay, Negative-Going OES to Q <sub>S</sub>	5.5 5.5	12.0 14.0			5.0 5.0	15.0 15.0	ns	
t <sub>PHZ</sub>	Propagation Delay, Negative-Going OES to QS	5.5 5.5	12.0 14.5			5.0 5.0	14.0 16.0	115	
t <sub>PZH</sub>	Turn On Time TOS to Q <sub>S</sub>	8.5 8.5	21.0 20.0			8.0 8.0	24.0 21.0	ns	
t <sub>DFT</sub>	Fall Through Time	45.0	80.0			35.0	95.0	ns	403-f
t <sub>AP</sub>	Parallel Appearance Time, ORE to Q <sub>0</sub> -Q <sub>3</sub>	-10.0	-1.0			-10.0	-1.0	ns	
t <sub>AS</sub>	Serial Appearance Time, ORE to Q <sub>S</sub>	-10.0	2.0			-10.0	2.0		

## **AC Operating Requirements**

		74F  T <sub>A</sub> = +25°C  V <sub>CC</sub> = +5.0V		5-	4F	74	4F		
Symbol	Parameter			T <sub>A</sub> , V <sub>CC</sub> = Mil		T <sub>A</sub> , V <sub>CC</sub> = Com		Units	Fig. No.
		Min	Max	Min	Max	Min	Max		
t <sub>s</sub> (H) t <sub>s</sub> (L)	Set-up Time HIGH or LOW  D <sub>S</sub> to Negative CPSI	1.0 1.0				1.0 1.0		ns	403-a, b
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold Time, HIGH or LOW D <sub>S</sub> to CPSI	3.5 3.5				3.5 3.5			
t <sub>s</sub> (L)	Set-up Time, LOW TTS to IRF Serial or Parallel Mode	0				0		ns	403-a, b g, h
t <sub>s</sub> (L)	Set-up Time, LOW Negative-Going ORE to Negative-Going TOS	0				0		ns	403-c, c
t <sub>s</sub> (L)	Set-up Time, LOW Negative-Going IES to CPSI	3.0				4.0		ns	403-b
t <sub>s</sub> (L)	Set-up Time, LOW Negative-Going TTS to CPSI	14.0				15.5		ns	403-b
t <sub>s</sub> (H) t <sub>s</sub> (L)	Set-up Time, HIGH or LOW Parallel Inputs to PL	0 0				0		ns	
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold Time, HIGH or LOW Parallel Inputs to PL	2.0 2.0				2.5 2.5			
t <sub>w</sub> (H) t <sub>w</sub> (L)	CPSI Pulse Width HIGH or LOW	5.0 3.0				6.0 5.0		ns	403-a, i
t <sub>w</sub> (H)	PL Pulse Width, HIGH	4.0				5.0		ns	403-g,
t <sub>w</sub> (L)	TTS Pulse Width, LOW Serial or Parallel Mode	3.5				4.0		ns	403-a, l c, d
t <sub>w</sub> (L)	MR Pulse Width, LOW	3.5				4.0		ns	403-f
t <sub>w</sub> (H)	TOP Pulse Width HIGH or LOW	4.5 3.5				5.5 4.0		ns	403-е
t <sub>w</sub> (H)	CPSO Pulse Width HIGH or LOW	4.5 3.0				5.5 4.0		ns	403-c,
t <sub>rec</sub>	Recovery Time MR to Any Input	5.0				5.5		ns	403-1

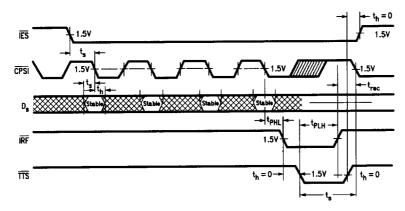
## **Timing Waveforms**



TL/F/9536-15

Conditions: stack not full, IES, PL LOW

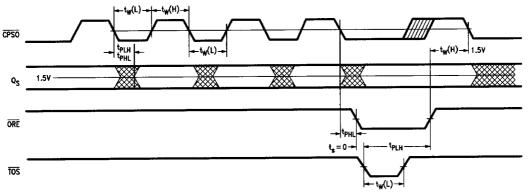
FIGURE 403-a. Serial Input, Unexpanded or Master Operation



TL/F/9536-16

Conditions: stack not full,  $\overline{\text{IES}}$  HIGH when initiated, PL LOW

FIGURE 403-b. Serial Input, Expanded Slave Operation

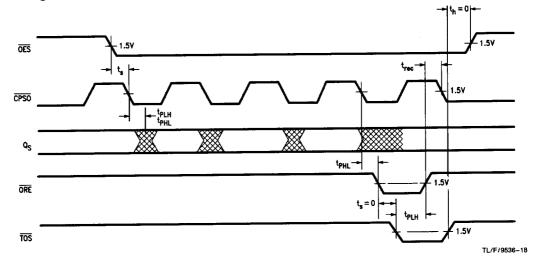


TL/F/9536-17

Conditions: data in stack, TOP HIGH,  $\overline{\text{IES}}$  LOW when initiated,  $\overline{\text{OES}}$  LOW

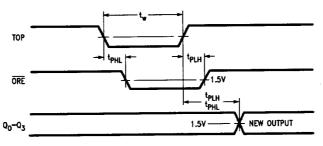
FIGURE 403-c. Serial Output, Unexpanded or Master Operation





Conditions: data in stack, TOP HIGH, IES HIGH when initiated

FIGURE 403-d. Serial Output, Siave Operation

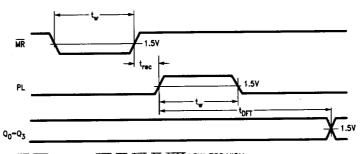


Conditions: IES LOW when initiated, OE, CPSO LOW; data available in stack

FIGURE 403-e. Parallel Output, 4-Bit Word or Master in Parallel Expansion

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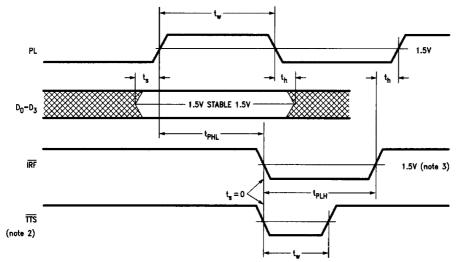
TL/F/9536-20



Conditions: TTS connected to TRF, TOS connected to ORE, IES, OES, OE, CPSO LOW, TOP HIGH

FIGURE 403-f. Fall Through Time

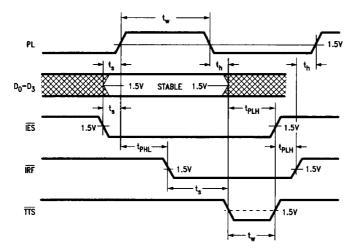
## Timing Waveforms (Continued)



TL/F/9536-21

Conditions: stack not full, IES LOW when initialized

FIGURE 403-g. Parallel Load Mode, 4-Bit Word (Unexpanded) or Master in Parallel Expansion



TL/F/9536-22

Conditions: stack not full, device initialized (Note 1) with IES HIGH

FIGURE 403-h. Parallel Load, Slave Mode

Note 1: Initialization requires a master reset to occur after power has been applied.

Note 2: TTS normally connected to IRF.

Note 3: If stack is full, IRF will stay LOW.